

Abstract of the Disclosure

In a coating and developing apparatus that forms a resist film on substrates such as semiconductor wafers, and develops substrates exposed by an aligner, times after the aligner unloads substrates until heating units (PEB) start heating the substrates are kept uniform. Exposed wafers are prevented from being left stagnant in an interface portion disposed between a region in which resist is coated and developed and the aligner. In the region in which resist is coated and developed, a first transferring means that successively executes transportation cycles to transfer substrates from upstream side modules to downstream side modules in a flow of processes of substrates. N heating units (PEB) are disposed (n is for example 5). Exposed wafers loaded into the heating units (PEB) are unloaded by the first transferring means after (n - 1) cycles including the transferring cycle of the first transferring means have elapsed.